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# QFET™

# FQP5N50C/FQPF5N50C

# **500V N-Channel MOSFET**

# **General Description**

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switched mode power supplies, active power factor correction, electronic lamp ballasts based on half bridge topology.

#### **Features**

- 5A, 500V,  $R_{DS(on)} = 1.4 \Omega @V_{GS} = 10 V$
- Low gate charge (typical 18nC)
- Low Crss (typical 15pF)
- Fast switching
- 100% avalanche tested
- · Improved dv/dt capability



# Absolute Maximum Ratings $T_C = 25^{\circ}C$ unless otherwise noted

Parameter		FQP5N50C	FQPF5N50C	Units
Drain-Source Voltage		500		V
Drain Current - Continuous (T <sub>C</sub> = 25°C)		5	5 *	Α
- Continuous (T <sub>C</sub> = 100°C)		2.9	2.9 *	Α
Drain Current - Pulsed	(Note 1)	20	20 *	Α
Gate-Source Voltage		± 30		V
Single Pulsed Avalanche Energy (No.		300		mJ
Avalanche Current	(Note 1)	5		Α
Repetitive Avalanche Energy	(Note 1)	7.3		mJ
Peak Diode Recovery dv/dt (Note 3)		4.5		V/ns
Power Dissipation (T <sub>C</sub> = 25°C)		73	38	W
- Derate above 25°C		0.58	0.3	W/°C
Operating and Storage Temperature Range		-55 to +150		°C
Maximum lead temperature for soldering purposes,		300		°C
	Drain-Source Voltage  Drain Current - Continuous (T <sub>C</sub> = 25°C) - Continuous (T <sub>C</sub> = 100°C)  Drain Current - Pulsed  Gate-Source Voltage  Single Pulsed Avalanche Energy  Avalanche Current  Repetitive Avalanche Energy  Peak Diode Recovery dv/dt  Power Dissipation (T <sub>C</sub> = 25°C) - Derate above 25°C  Operating and Storage Temperature Range	$ \begin{array}{c} \text{Drain-Source Voltage} \\ \text{Drain Current} & \text{- Continuous } (T_C = 25^{\circ}\text{C}) \\ & \text{- Continuous } (T_C = 100^{\circ}\text{C}) \\ \end{array} $ $ \begin{array}{c} \text{Drain Current} & \text{- Pulsed} & \text{(Note 1)} \\ \text{Gate-Source Voltage} \\ \text{Single Pulsed Avalanche Energy} & \text{(Note 2)} \\ \text{Avalanche Current} & \text{(Note 1)} \\ \text{Repetitive Avalanche Energy} & \text{(Note 1)} \\ \text{Peak Diode Recovery dv/dt} & \text{(Note 3)} \\ \text{Power Dissipation } (T_C = 25^{\circ}\text{C}) \\ & \text{- Derate above } 25^{\circ}\text{C} \\ \text{Operating and Storage Temperature Range} \\ \text{Maximum lead temperature for soldering purposes,} \\ \end{array} $	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$

<sup>\*</sup> Drain current limited by maximum junction temperature

## **Thermal Characteristics**

Symbol	Parameter	FQP5N50C	FQPF5N50C	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	1.71	3.31	°C/W
$R_{\theta JS}$	Thermal Resistance, Case-to-Sink Typ.	0.5		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62.5	62.5	°C/W

Symbol	Parameter	Test Conditions		Тур	Max	Units
Off Cha	aracteristics					
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$				V
ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250 μA, Referenced to 25°C		0.5		V/°C
I <sub>DSS</sub>	Zara Oata Valla va Basis Oamasi	V <sub>DS</sub> = 500 V, V <sub>GS</sub> = 0 V			1	μΑ
	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 400 V, T <sub>C</sub> = 125°C			10	μΑ
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	V <sub>GS</sub> = 30 V, V <sub>DS</sub> = 0 V			100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	$V_{GS} = -30 \text{ V}, V_{DS} = 0 \text{ V}$			-100	nA
On Cha	racteristics					
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$			4.0	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 2.5A		1.14	1.4	Ω
9 <sub>FS</sub>	Forward Transconductance	$V_{DS} = 40 \text{ V}, I_D = 2.5 \text{A}$ (Note 4)		5.2		S
	ic Characteristics			100	005	
Ciss	Input Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$		480	625	pF
Coss	Output Capacitance	f = 1.0 MHz		80	105	pF
C <sub>rss</sub>	Reverse Transfer Capacitance			15	20	pF
Switchi	ing Characteristics					
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> = 250 V, I <sub>D</sub> = 5A,		12	35	ns
t <sub>r</sub>	Turn-On Rise Time	$R_G = 25 \Omega$		46	100	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	- 1.6 - 1 - 1		50	110	ns
t <sub>f</sub>	Turn-Off Fall Time	(Note 4, 5)		48	105	ns
Qg	Total Gate Charge	$V_{DS} = 400 \text{ V}, I_{D} = 5A,$		18	24	nC
Q <sub>gs</sub>	Gate-Source Charge	V <sub>GS</sub> = 10 V		2.2		nC
Q <sub>gd</sub>	Gate-Drain Charge	(Note 4, 5)		9.7		nC
Drain-S	Source Diode Characteristics ar	nd Maximum Ratings				
I <sub>S</sub>	Maximum Continuous Drain-Source Diode Forward Current				5	Α
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode Forward Current				20	Α
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 5 A			1.4	V
t <sub>rr</sub>	Reverse Recovery Time	$V_{GS} = 0 \text{ V}, I_{S} = 5 \text{ A},$		263		ns
Q <sub>rr</sub>	Reverse Recovery Charge	$dI_F / dt = 100 A/\mu s$ (Note 4)		1.9		μС

- Notes: 
  1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L = 21.5 mH, I<sub>AS</sub> = 5A, V<sub>DD</sub> = 50V, R<sub>G</sub> = 25 Ω, Starting T<sub>J</sub> = 25°C 3. I<sub>SD</sub> ≤ 5A, di/dt ≤ 200A/μs, V<sub>DD</sub> ≤ BV<sub>DSS</sub>, Starting T<sub>J</sub> = 25°C 4. Pulse Test : Pulse width ≤ 300μs, Duty cycle ≤ 2% 5. Essentially independent of operating temperature

# **Typical Characteristics**

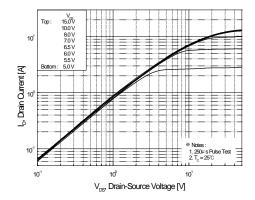


Figure 1. On-Region Characteristics

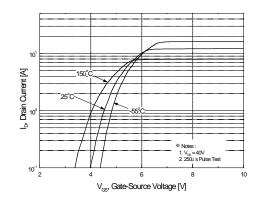


Figure 2. Transfer Characteristics

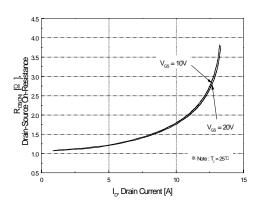


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

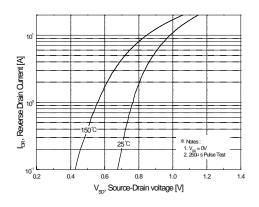


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

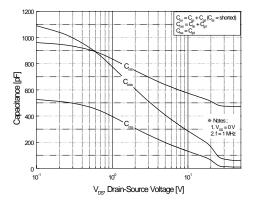


Figure 5. Capacitance Characteristics

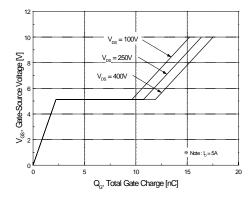


Figure 6. Gate Charge Characteristics

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# Typical Characteristics (Continued)

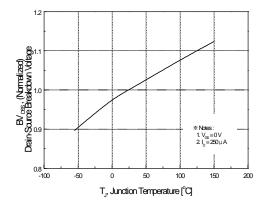


Figure 7. Breakdown Voltage Variation vs Temperature

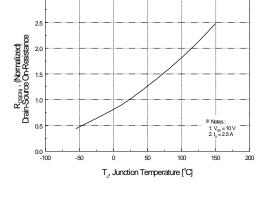


Figure 8. On-Resistance Variation vs Temperature

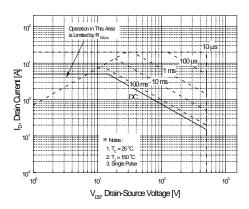


Figure 9-1. Maximum Safe Operating Area for FQP5N50C

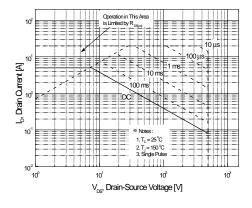


Figure 9-2. Maximum Safe Operating Area for FQPF5N50C

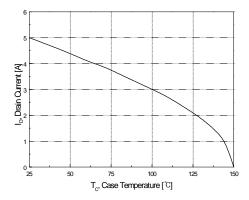


Figure 10. Maximum Drain Current vs Case Temperature

# Typical Characteristics (Continued)

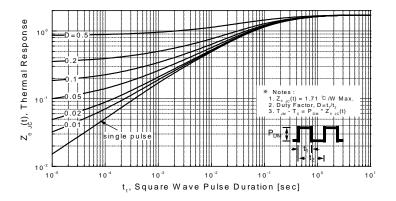


Figure 11. Transient Thermal Response Curve for FQP5N50C

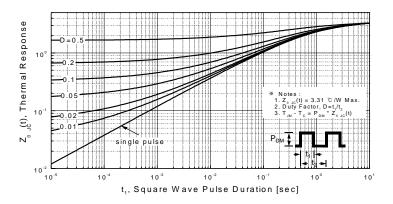
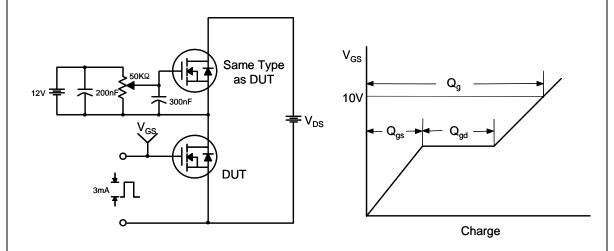


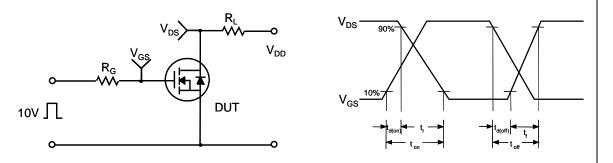
Figure 11-2. Transient Thermal Response Curve for FQPF5N50C

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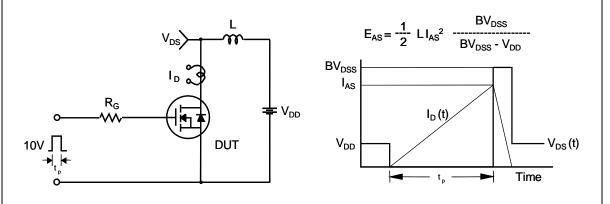
# **Gate Charge Test Circuit & Waveform**



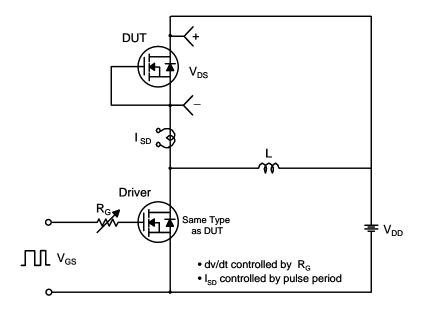
# **Resistive Switching Test Circuit & Waveforms**

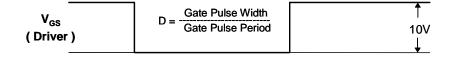


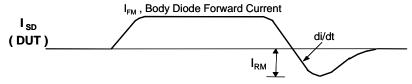
# **Unclamped Inductive Switching Test Circuit & Waveforms**



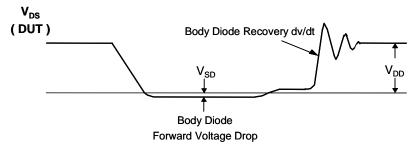
# Peak Diode Recovery dv/dt Test Circuit & Waveforms







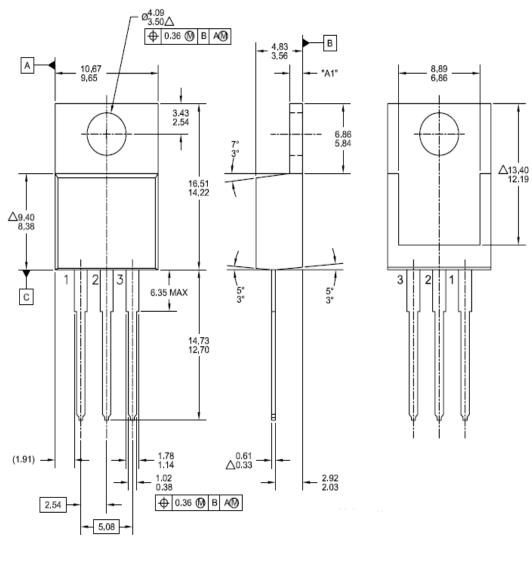
Body Diode Reverse Current

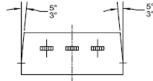


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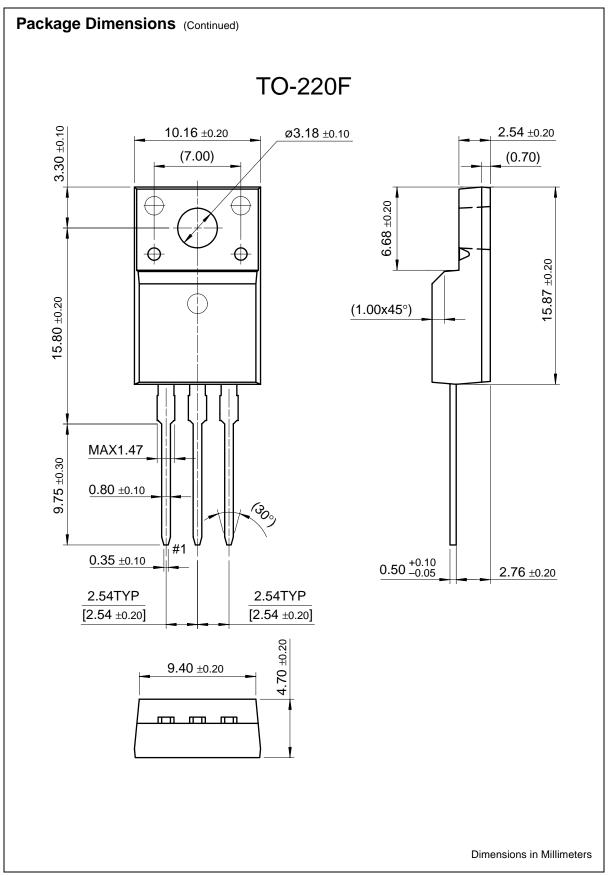


TO - 220





Dimensions in Millimeters



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